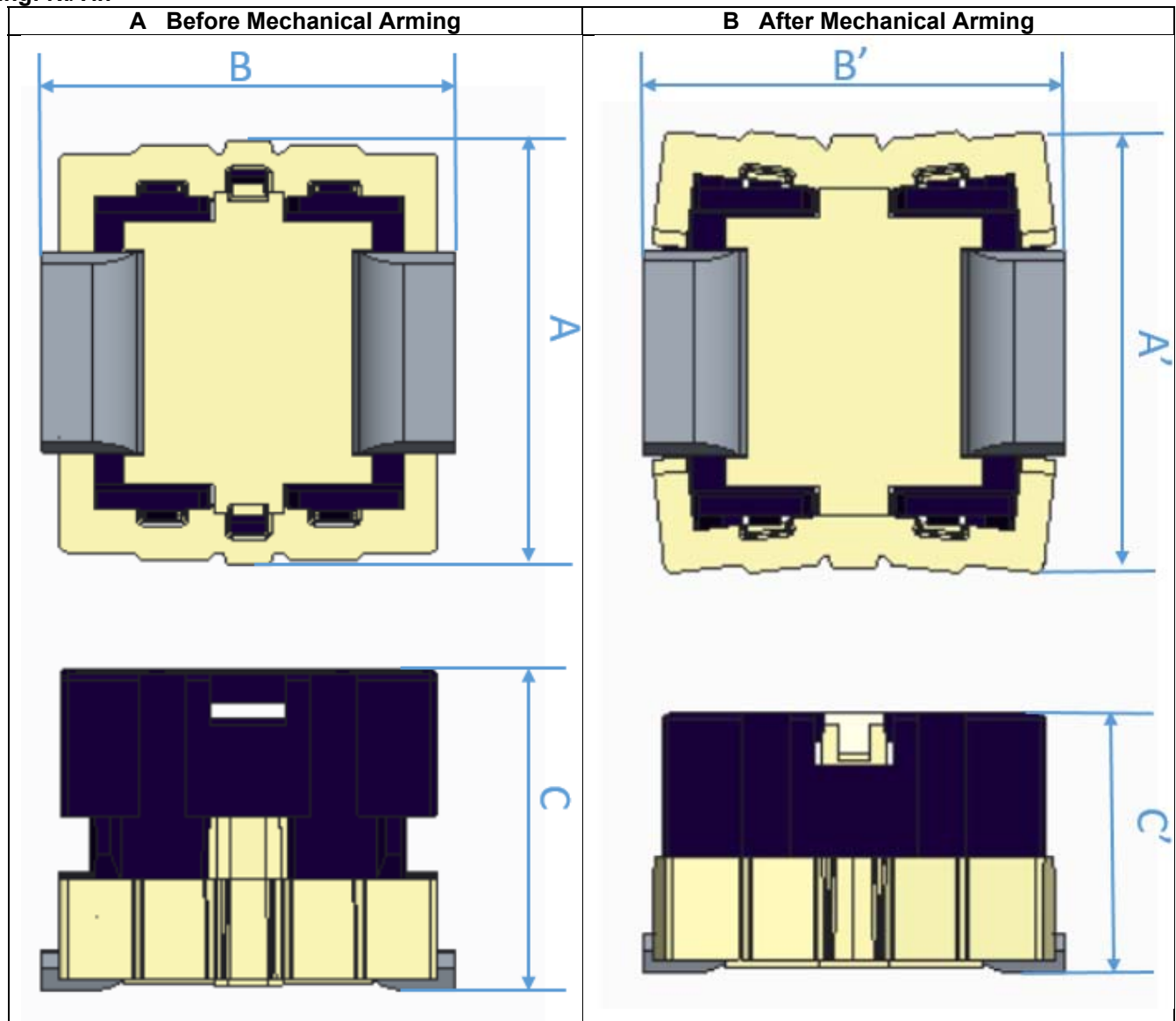


**Specification Status: Released**

HC RTP-mini-C is low resistance, surface mountable thermal protector which can be installed on PCB using surface mount assembly and reflow process. By using specified solder paste in the user's system, HC RTP-mini-C can protect the components on the user's PCB from overheating when the temperature is higher than the melting point of the solder paste.

**1. Configuration and Dimension:**

**Terminal Material:** C1100 1/2H (Tough-Pitch Copper)  
**Thickness:** 0.6mm  
**Plating:** Ni/Tin

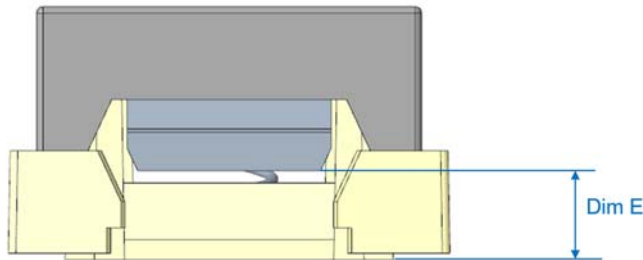


**Table-1. Dimensions:**

|    | Before Mechanical Arming |       |       |       |       |       | After Mechanical Arming |       |       |       |       |       |
|----|--------------------------|-------|-------|-------|-------|-------|-------------------------|-------|-------|-------|-------|-------|
|    | A                        |       | B     |       | C     |       | A'                      |       | B'    |       | C'    |       |
|    | Min                      | Max   | Min   | Max   | Min   | Max   | Min                     | Max   | Min   | Max   | Min   | Max   |
| mm | 6.60                     | 7.00  | 6.45  | 6.80  | 4.8   | 5.2   | 6.83                    | 7.83  | 6.45  | 6.80  | 3.8   | 4.2   |
| in | 0.260                    | 0.276 | 0.254 | 0.268 | 0.189 | 0.205 | 0.269                   | 0.308 | 0.254 | 0.268 | 0.150 | 0.165 |

**Dim E is Terminal lift dimension post open from base bottom to terminal .**

|       |         |
|-------|---------|
| Dim E | Min     |
|       | 1.10 mm |



## 2. Marking: Each lot of devices is marked on the body for traceability.

- □ \_ C (Terminal type)
- □□□□ \_ Batch Number

## 3. Ratings & Spring Characteristics

**Table 2. Ratings**

| DC Open Voltage<br>(Vdc) | DC Interrupt Current<br>@ 16Vdc<br>(A) | Operating Temperature<br>(°C) |     | Resistance @ 23°C<br>(μΩ) |      |     |
|--------------------------|--|-------------------------------|-----|---------------------------|------|-----|
|                          |  | Min                           | Max | Min                       | Typ. | Max |
| Max<br>16                | Max<br>500                             | -55                           | 150 | 53                        | 72   | 91  |

Note 1: Performance capability at these conditions can be influenced by board design.

Performance should be verified in the user's system.

Note 2: Resistance should be measured by a 4 wired method unless otherwise specified.

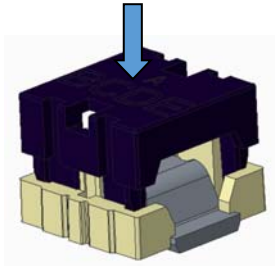
**Table 3. Cap Integrity**

|                     | Min | Typ. | Max | Units |
|---------------------|-----|------|-----|-------|
| Vertical pull force |     |      | 3   | N     |

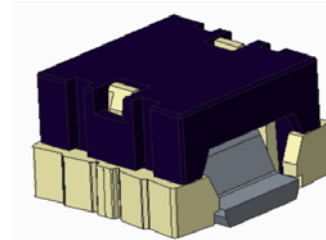
## 4. Arming

Arming is to occur after surface mount installation.

Method: Cap depressed manually or by mechanical plunger



Downward force required for mechanical arming



Device after mechanical arming completed

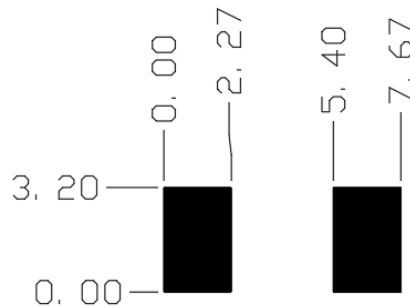
**Warning:** The device will not function without proper arming.

If the device will be depressed by mechanical plunger, the plunger speed should be verified in the user's process.

**Table 4. Arming Recommendation:**

| Description                          | Min. | Typ. | Max. | Units |
|--------------------------------------|------|------|------|-------|
| Arming Force (Normal to PCB surface) | 25   | 32.5 | 40   | N     |
| Distance of travel                   | 0.94 | 1.00 | 1.06 | mm    |

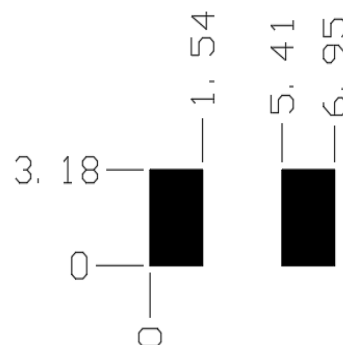
## 5. Recommended Solder Pad Layout (Dimensions in mm):



## 6. Recommended Solder Stencil Opening (Dimensions in mm):

Stencil thickness used for testing: 0.110 ~ 0.140mm

Solder paste used for testing: Indium 5.8LS, SAC 305 (96.5% tin, 3% silver and 0.5% copper)

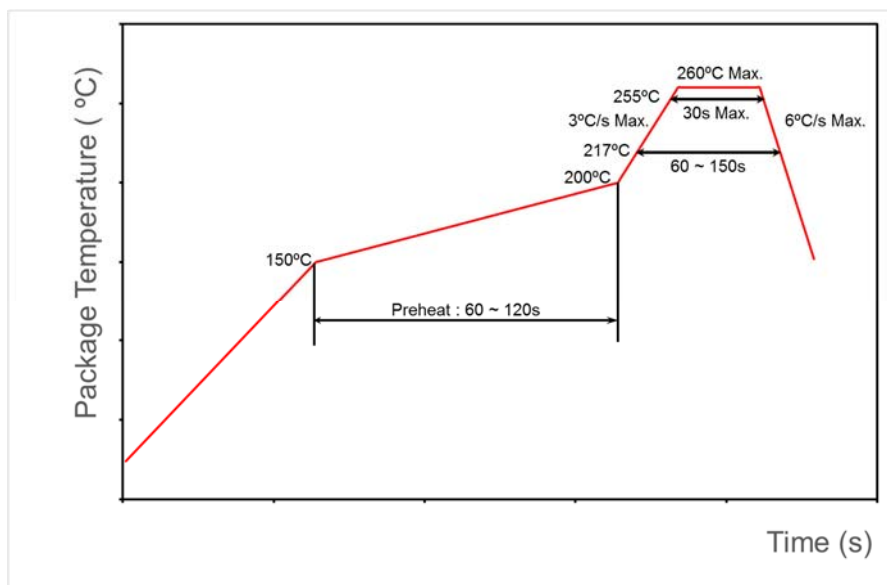


## 7. Solder Reflow Recommendation

As per JEDEC J-STD-020D

| Classification Reflow Profiles   |                  |
|--|------------------|
| Profile Feature  | Pb-Free Assembly |
| Average ramp-up rate ( $T_{SMAX}$ to $T_P$ )   | 3°C/second max.  |
| <b>Preheat</b>   |                  |
| ● Temperature min. ( $T_{SMIN}$ )  | 150°C            |
| ● Temperature max. ( $T_{SMAX}$ )  | 200°C            |
| ● Time ( $T_{SMIN}$ to $T_{SMAX}$ )  | 60 - 120 seconds |
| <b>Time maintained above:</b>  |                  |
| ● Temperature ( $T_L$ )  | 217°C            |
| ● Time ( $t_L$ )   | 60 - 150 seconds |
| <b>Peak/Classification temperature (<math>T_P</math>)</b>  | 260°C            |
| <b>Time (<math>t_P</math>) within 5°C of the specified classification temperature (<math>t_c</math>)</b> |                  |
| Time ( $t_c$ )   | 30 seconds max.  |
| <b>Ramp-down rate</b>  | 6°C/second max.  |
| <b>Time 25°C to peak temperature</b>   | 8 minutes max.   |

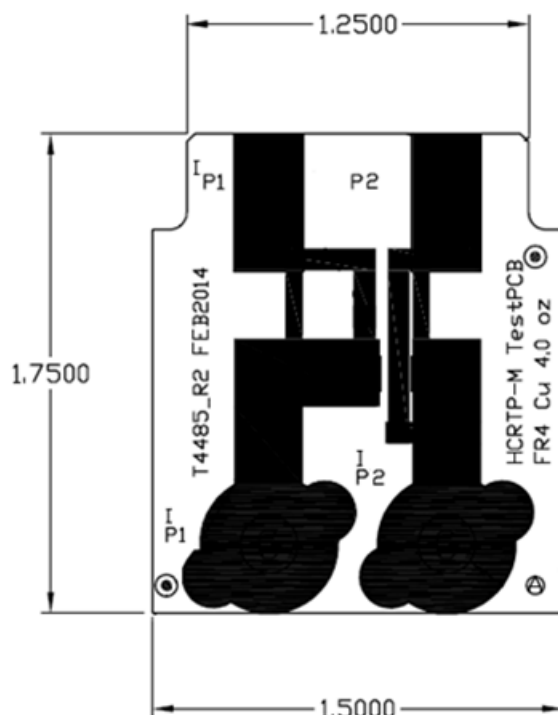
Note: All temperatures refer to topside of the package, measured on the package body surface.



## 8. Referenced Performance

Results obtained on 44.4mm x 57.2 mm x 1.6mm of 2-sided FR4 board T4485 with 4.0 oz. Copper Trace.  
HC RTP-mini-C device pad connection of

- 374 sq. mm 4.0 oz. copper heat spreader connected to P1 Pad.
- 327 sq. mm 4.0 oz. copper heat spreader connected to P2 Pad.



HC RTP-mini-C device surface-mounted on test board T4485 using solder paste SAC 305 with recommended pad layout and solder stencil opening and thickness.

Post reflow resistance based on SMT 1x reflow as outlined in solder reflow recommendation.

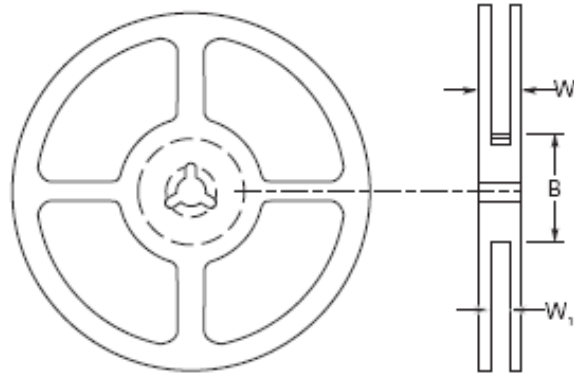
Results are highly installation-dependent. Users should confirm for their own application.

**Table 5. Referenced performance.**

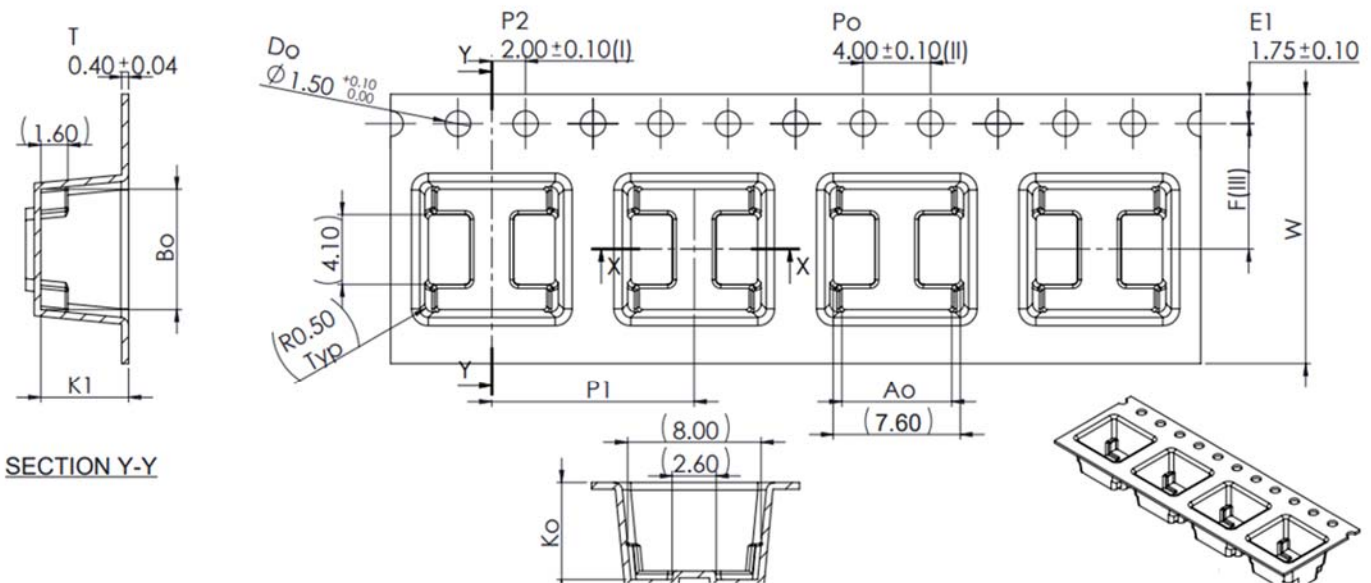
| Performances           |           | Min | Typ. | Max | Units |
|------------------------|-----------|-----|------|-----|-------|
| Post Reflow Resistance | @ 23±3°C  | 60  | 110  | 160 | μΩ    |
|                        | @ 150±3°C | 120 | 165  | 210 |       |
| Hold Current           | @ 23±3°C  |     |      | 90  | A     |
|                        | @ 140±3°C |     |      | 45  |       |
| Max Interrupt Current  | 16Vdc     |     |      | 500 | A     |
| Open Temperature       | Zero Bias | 212 | 220  | 228 | °C    |

Post reflow resistance should be measured by a 4 wired method.

## 9. Packaging Information:



|      | B    |      | W <sub>1</sub> |      | W <sub>2</sub> |      |
|------|------|------|----------------|------|----------------|------|
|      | Min  | Max  | Min            | Max  | Min            | Max  |
| mm   | 79   | 81   | 16.5           | 18.5 | 20.5           | 22.5 |
| Inch | 3.11 | 3.19 | 0.65           | 0.73 | 0.81           | 0.89 |



|      | Ao   |      | Bo   |      | Ko   |      | K1   |      | F    |      | P1   |      | W    |      |
|------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|
|      | Min  | Max  | Min  | Max  | Min  | Max  | Min  | Max  | Min  | Max  | Min  | Max  | Min  | Max  |
| mm   | 6.46 | 6.66 | 7.04 | 7.24 | 5.6  | 5.8  | 5.1  | 5.3  | 7.4  | 7.6  | 11.9 | 12.1 | 15.7 | 16.3 |
| Inch | 0.25 | 0.26 | 0.28 | 0.29 | 0.22 | 0.23 | 0.20 | 0.21 | 0.29 | 0.30 | 0.47 | 0.48 | 0.62 | 0.64 |

Precedence: This specification takes precedence over documents referenced herein.  
Effectivity: Reference documents shall be the issue in effect on the date of invitation for bid.

### Important Installation Instructions :

- Note 1: HC RTP-mini-C devices are to be board-mounted using solder paste SAC 305 (96.5% Tin, 3% Silver, and 0.5% Copper).  
Note 2: HC RTP-mini-C devices are not compatible with conformal coating. If selective coatings are used, avoid covering the HC RTP-mini-C device, and it needs to be verified in the user's system with their own risk.  
Note 3: HC RTP-mini-C devices are not to be reworked in any manner which affects values stated in Table 2.

### MATERIALS INFORMATION

#### RoHS Compliant

Directive 2002/95/EC  
Compliant

#### ELV Compliant

Directive 2000/53/EC  
Compliant

#### Pb-Free



#### Halogen Free\*



\* Halogen Free refers to: Br≤900ppm, Cl≤900ppm, Br+Cl≤1500ppm.

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